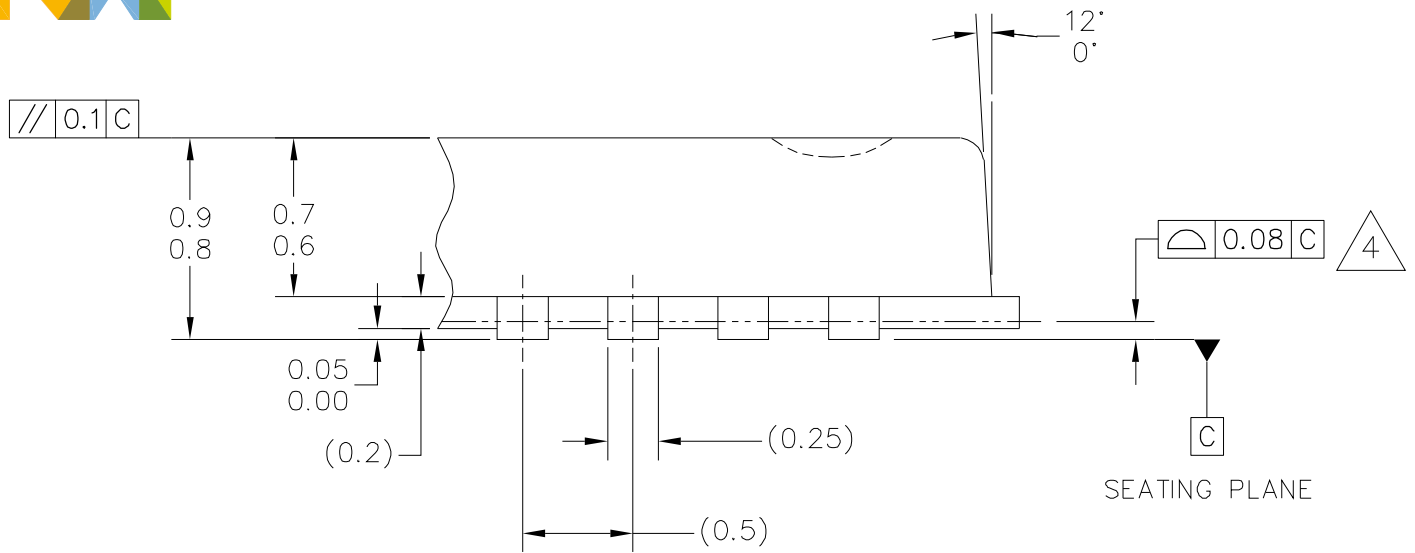


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|--|-------------------------------|----------------------------|
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| TITLE: THERMALLY ENHANCED QUAD<br>FLAT NO LEAD PACKAGE (QFN),<br>48 TERMINAL, 0.5 PITCH (7 X 7 X 0.85),<br>PUNCH SINGULATION | DOCUMENT NO: 98ASA10825D      | REV: A                     |
|  | STANDARD: JEDEC MO-220 VKKD-2 |                            |
|  | SOT619-21                     | 15 MAR 2016                |



DETAIL G  
VIEW ROTATED 90° CW

|  |                               |                            |
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|  | STANDARD: JEDEC MO-220 VKKD-2 |                            |
|  | SOT619-21                     | 15 MAR 2016                |



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. THE PIN #1 IDENTIFIER MUST BE EXISTED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
7. MIN METAL GAP SHOULD BE 0.20MM.

|  |                           |                               |             |
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|  |                           | SOT619-21                     | 15 MAR 2016 |